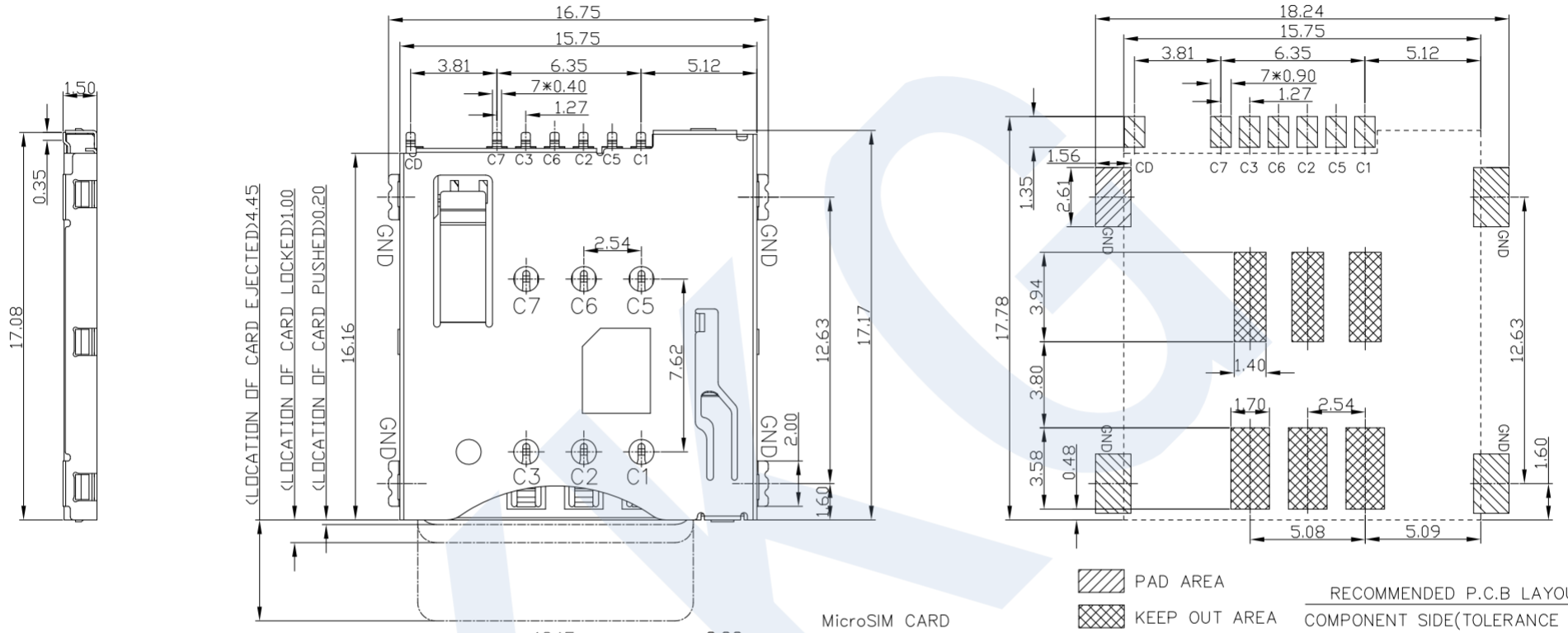
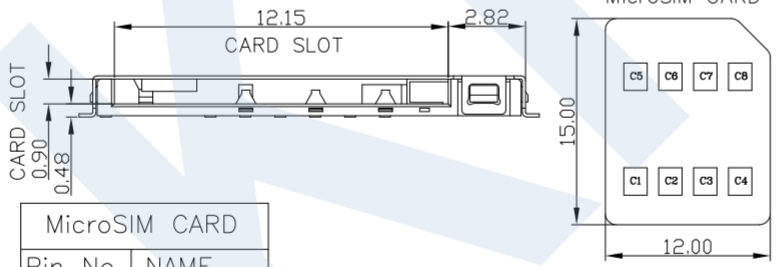
REV.	ECN	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	2016.03.09	WEI		WEI





TECHNICAL CHARACTERISTICS

1.General Characteristics
- Dimensions: 15.75LX17.17WX1.50H mm
- Weight: Approx 0.4±0.1g
- Durability: 1500 cycles min.

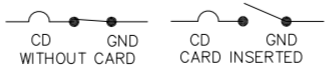
2.Electrical Characteristics
- Contact resistance;
- Date Contact: 150mΩ max
- CD Switch: 500mΩ max
- Insulation resistance: >1000MΩ/500V DC

3.Solderability
- Vapor phase: 215°C,30sec.Max
- IR reflow: 250°C,5sec.Max
- Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics
- Operating temperature: −40°C~+85°C
- Operating humidity: 10%~+95%RH

MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



SWITCH OPERATION DIAGRAM

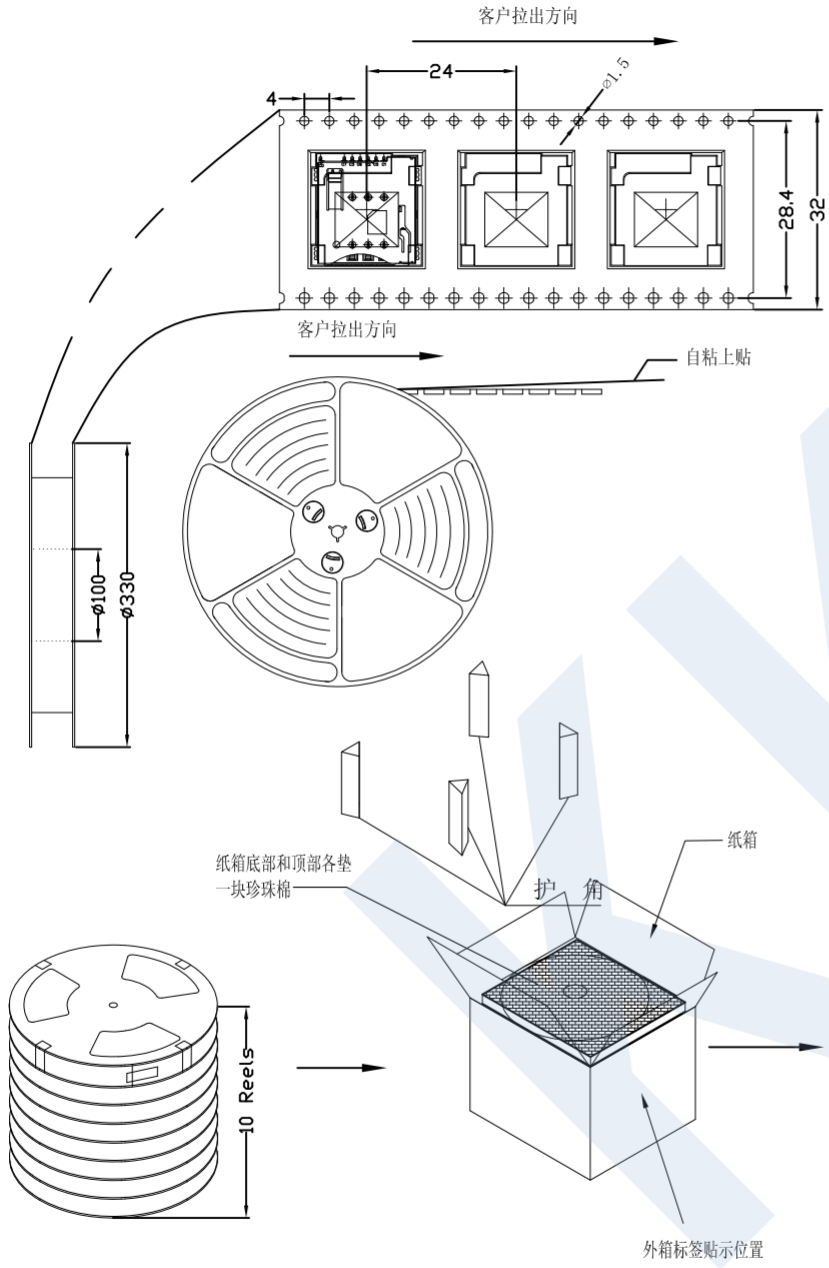
ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	CD SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	SMT area:Gold plated
5	COIL SPRING	1	SWP	
6	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
7	CAM PIN	1	Stainless Steel	

MILLIMETERS	INCH
X.° ± 2°	X.° ± 2°
.X ±0.30	.XX ±0.012
.XX ±0.20	.XXX ±0.008
.XXX± 0.10	.XXXX± 0.004

UNITS MM
MAT'L SEE NOTES
FINISH SEE NOTES
QTY SEE NOTES

KKG

PART NUMBER:
TITLE: MicroSIM PUSH H1.5
APPD: WEI
DWG NO:
CHKD:
DR: WEI
SCALE 1:1 | SHEET 1/2 | REV. A0

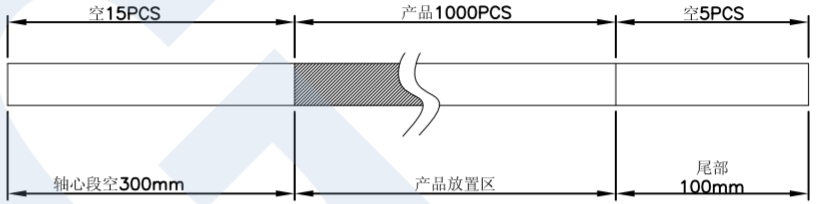


将10卷产品放入箱内

NOTES

1.每卷包装数量:1000PCS/每卷

2.卷带包装方式:



3.每箱包装数量:10000PCS/箱

4.纸箱350mm*350mm*440mm(内部尺寸),材质K=K

MILLIMETERS	INCH
X.° ± 2°	X.° ±
.X ±0.20	.XX ±
.XX ±0.10	.XXX ±
.XXX± 0.05	.XXXX±

UNITS	MM
MAT'L	SEE NOTES
FINISH	SEE NOTES
QTY	SEE NOTES

KKG

PART NUMBER:	TITLE: MicroSIM PUSH H1.5(卷装组装图)
APPD: WEI	DWG NO.:
CHKD: ---	
DR: QEI	

SCALE	SHEET	REV.
1:1	2/2	A0